

Japan TC Chapter of 3DS-IC Global Technical Committee Meeting Summary and Minutes

Japan Standards Fall 2015 Meetings
Friday, October 16, 2015, 3:50 p.m. - 5:30 p.m. [JST]
SEMI Japan office, Tokyo, Japan

Next Committee Meeting

Friday, February 5, 2016, 3:15 p.m. – 5:00 p.m. [JST]
Japan Standards Winter 2016 Meetings, Tokyo, Japan

Committee Announcements (optional)

None

Table 1 Meeting Attendees

Italics indicates virtual participants

Co-Chairs: Masahiro Tsuruya (iNEMI), Haruo Shimamoto (AIST)

SEMI Staff: Chie Yanagisawa (SEMI Japan)

Attendee: 25 + **SEMI:** 1

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Acteon	<i>Komatsu</i>	<i>Shoji</i>	Micron Memory Japan	Sonobe	Kaoru
Advantest	Ichikawa	Masayoshi	Miraial	Umeda	Toshiya
AIST	Shimamoto	Haruo	Nidec-Read Corporation	Miyazaki	Yoko
AiT	Kato	Kazunori	Nihon Entegris	Fukunaga	Tsukasa
Corning Japan	Yamazaki	Kuniaki	Nikon	Shimoda	Toshimasa
DISCO	Masuchi	Sumio	Samusung	Kajinami	Masato
Fasford Technology	Mochizuki	Masayuki	Senju Metal Industry	Roppoingi	Takahiro
Fasford Technology	Tsuchiya	Kunihiro	Shin-Etsu Polymer	Shinozuka	Nobushiro
Fuji Film	Abe	Hirofumi	Shin-Etsu Polymer	Wakabayashi	Ryo
Hitachi High-Technologies	Yoshino	Eiji	SUMCO	Nakai	Tetsuya
Hitachi Kokusai Electric	Matsuda	Mitsuhiro	Toray Engineering	Asahi	Noboru
iNEMI	Tsuruya	Masahiro	Self	Yoshise	Masanori
Intel	Tomita	Yoshihiro	SEMI Japan	Yanagisawa	Chie

** alphabetical order by company name*

Table 2 Leadership Changes

<i>Group</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 Ballot Results (or move to Section 4, Ballot Review)

Passed ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
None		

Table 4 Authorized Ballots (or move to Section 7, New Business)

<i>#</i>	<i>When</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

Table 5 Authorized Activities (or move to Section 7, New Business)

#	Type	SC/TF/WG	Details
None			

Table 6 New Action Items (or move to Section 8, Action Item Review)

Item #	Assigned to	Details
20151016-1	SEMI Staff	To ask the reason why North America TC Chapter discontinued Doc. 5692 and Doc. 5174.

Table 7 Previous Meeting Actions Items (or move to Section 8, Action item Review)

Item #	Assigned to	Details
None		

1 Welcome, Reminders, and Introductions

Masahiro Tsuruya (iNEMI) called the meeting to order at 3:50 a.m. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

2 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting.

Motion:	To approve the previous meeting minute with minor editorial change
By / 2nd:	Haruo Shimamoto (AIST) / Kaoru Sonobe (Micron Japan)
Discussion:	None
Vote:	22 in favor and 0 opposed. Motion passed.

3 Liaison Reports

3.1 3DS-IC North America TC Chapter

The report of North America TC Chapter was the same presented at the previous Japan TC Chapter meeting held on September 7, 2015, but Chie Yanagisawa (SEMI Japan) reported for new TC Members at the meeting. Of note:

- Leadership
 - Committee Co-chairs
 - Sesh Ramaswami (Applied Materials)
 - Rich Allen (NIST)
 - Chris Moore (BayTech-Resor)
- Overview
 - Bonded Wafer Stacks
 - Create and/or modify specifications that reflect bonded wafer stacks parameters and the wafer bonding process.
 - Inspection & Metrology
 - Develop standards for metrology and inspection methods to be used in measuring the properties of TSV's, bonded wafer stacks, and dies used in the 3DS-IC manufacturing process.
- Meeting Information
 - Last meeting
 - July 14 for SEMICON West 2015, San Francisco, California

- Next meeting
 - November 3 for the NA Fall 2015 Meetings, San Jose, California

Action Item 1: SEMI Staff to ask the reason why North America TC Chapter discontinued Doc. 5692 and Doc. 5174.

Attachment: [01_NA 3DS-IC report September 2015](#)

3.2 3DS-IC Taiwan TC Chapter

Chie Yanagisawa (SEMI Japan) reported for the Taiwan TC Chapter. Of note:

- Leadership
 - Tzu-Kun Ku (ITRI)
 - Wendy Chen (King Yuan Electronics)
 - Roger Hwang (ASE)
- Organization
 - Testing Task Force
 - Middle End Process Task Force
- Meeting Information
 - Last meeting
 - October 6, 2015, SEMI Taiwan office
 - Next meeting
 - Q1CY2016 (pending next ballot requirement)

Attachment: [02_Taiwan 3DS-IC Liaison Report Oct 2015](#)

3.3 SEMI Staff Report

Chie Yanagisawa (SEMI Japan) reported for SEMI Staff report as attached. The contents are as following:

- Global SEMI Events
- Global Standards Meetings Schedule
- Ballot Critical Dates
- Publication Update
- A&R Ballot Review
- New Requirements/Process Reminders for TC Chapter Meetings
- Contact Information

Attachment: [03_SEMI Staff Report 2015.10.15](#)

4 Ballot Review

None

5 Subcommittee & Task Force Reports

5.1 Steering Group

Haruo Shimamoto (AIST) reported the summary of replies to the questionnaire distributed at 3DS-IC Standardization Workshop held on September 7, 2015 with mentioning the topics to be standardized in this activity. Details are found in the attachment.

Yoshihiro Tomita (Intel) suggested the following items in order that all 3DS-IC TC members participating in Japan TC Chapter would understand Steering Group activities well.

- The Steering Group is formed under the 3DS-IC Japan TC Chapter, then the meeting notice and meeting minutes will be shared with all the members above mentioned.

- The scope of this steering group is defined as below:
 - Buy-in more OEMs to this steering activities and ask to participate standard development.
 - Develop the workshop planning to promote the latest technologies and market trends on the area.
 - Brainstorm the areas of potential taskforce activities, and propose the taskforce formation to the Technical Committee Brainstorming discussion
- The outcome from the Steering Group meetings will be reported to the 3DS-IC Japan TC Chapter. When needed the Steering Group will ask for approval by the Japan TC Chapter to proceed the actions per SEMI Standards Regulations.
- The Steering Group may ask additional new leadership to enforce the group activities.
- These items above could be amended as needed base and the revised or newly added items is required the approval by the Japan TC Chapter.

Motion:	To approve the proposed items and activities above mentioned.
By / 2nd:	Yoshihiro Tomita (Intel) / Hirofumi Abe (Fuji Film)
Discussion:	None
Vote:	22 in favor and 0 opposed. Motion passed.

[Attachment: 04_150907_3DSIC-WS_QuestionnaireSummary151016, 05_3DS-IC TC Steering Group_WW42 15](#)

6 Old Business

Masahiro Tsuruya (iNEMI) reported that Ballot 5835, related to 3DS-IC, developed by Thin Chip Handling Task Force under the Assembly & Packaging Japan TC Chapter was passed at the Japan TC Chapter meeting held on October 16, 2016, right before this meeting.

Haruo Shimamoto (AIST) explained that Thin Chip Handling Task Force was active under the Assembly & Packaging Japan TC Chapter.

Haruo Shimamoto (AIST) explained that it was still under discussion whether Tape Adhesive Strength Measurement TF should be formed under 3DS-IC Japan TC Chapter or Packaging TC Chapter. Haruo Shimamoto will update the status at the next TC Chapter meeting.

7 New Business

None

8 Action Item Review

8.1 Open Action Items

None

8.2 New Action Items

Action Item 1: SEMI Staff to ask the reason why North America TC Chapter discontinued Doc. 5692 and Doc. 5174.

9 Next Meeting and Adjournment

The next meeting of the 3DS-IC Japan TC Chapter is scheduled for Friday, February 5, 2016, 3:15 p.m. – 5:00 p.m. at Japan Standards Winter 2016 Meetings at SEMI Japan office in Tokyo.

Respectfully submitted by:
Chie Yanagisawa
Senior Standard Coordinator
SEMI Japan
Phone: +81.3.3222.5863
Email: cyanagisawa@semi.org

Minutes approved by:

Masahiro Tsuruya (iNEMI), Co-chair	February 5, 2016
Haruo Shimamoto (AIST), Co-chair	February 5, 2016

Table 8 Index of Available Attachments #1

#	<i>Title</i>	#	<i>Title</i>
01	NA 3DS-IC report September 2015	04	150907_3DSIC-WS_QuestionnaireSummary151016
02	Taiwan 3DS-IC Liaison Report Oct 2015	05	3DS-IC TC Steering Group_WW42 15
03	SEMI Staff Report 2015.10.15		

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.